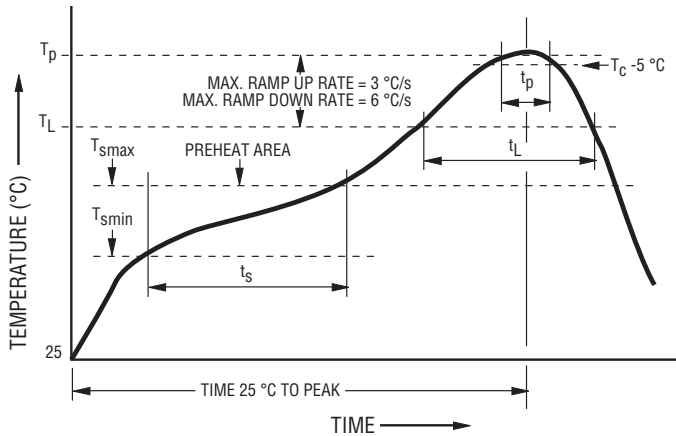


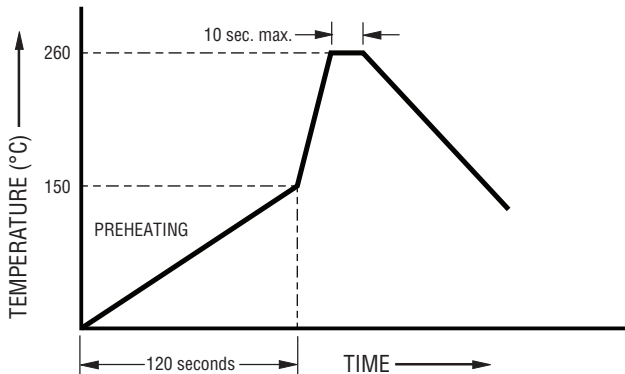
**Solder Reflow Recommendations**



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. ( $T_{smin}$ ) Temperature Max. ( $T_{smax}$ ) Time ( $t_s$ ) from ( $T_{smin}$ to $T_{smax}$ )	150 °C 200 °C 60~120 seconds
Ramp Up Rate ( $T_l$ to $T_d$ )	3 °C / second max.
Liquidous Temperature ( $T_l$ ) Time ( $t_L$ ) maintained above $T_l$	217 °C 60~150 seconds
Peak Package Body Temperature ( $T_d$ )	260 °C
Time ( $t_p$ )* within 5 °C of the specified classification temperature ( $T_c$ )	30 seconds*
Ramp Down Rate ( $T_d$ to $T_l$ )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

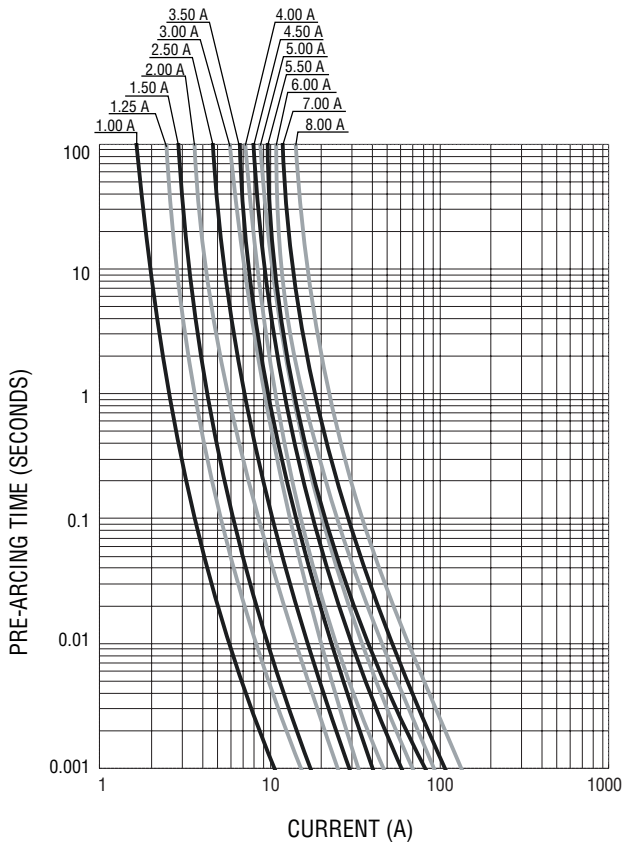
\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

**Recommended Temperature Profile for Wave Soldering**

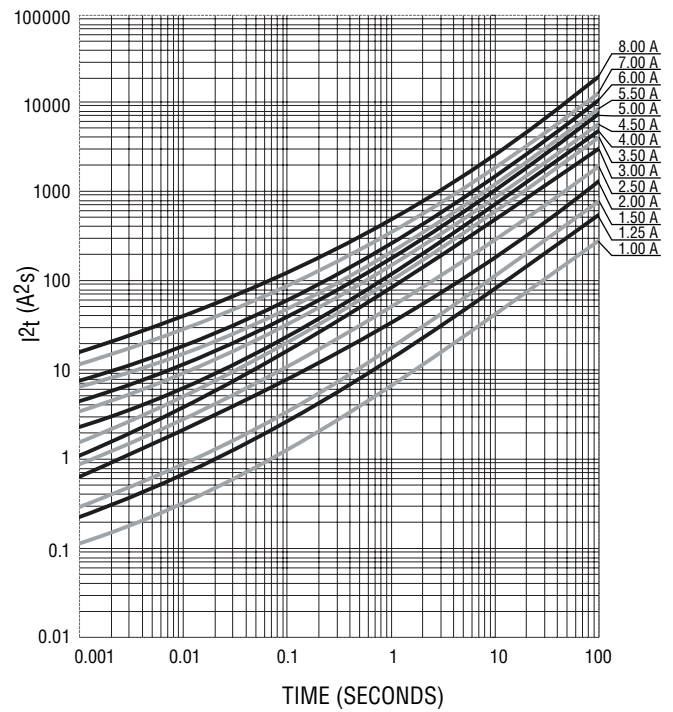


Wave soldering is suitable for 1206 size models.

Average Pre-Arcing Time vs. Current Curves



Average  $I^2t$  vs. t Curves



REV. B 03/18

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.